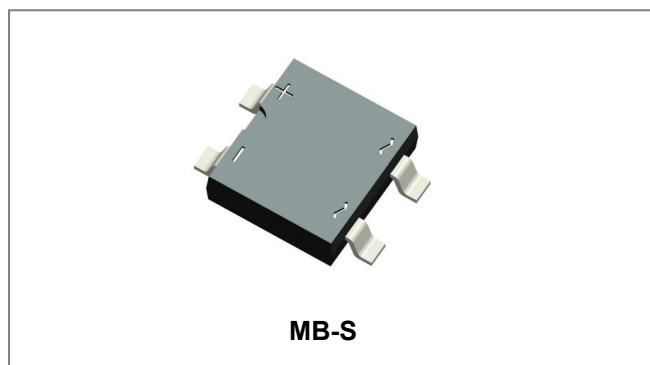


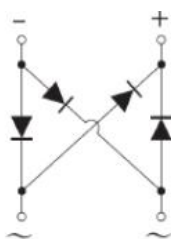
RMB2S-RMB6S Miniature Glass Passivated Fast Recovery Surface Mount Bridge Rectifiers



Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260° C/ 10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbols marked on case
- Mounting Position: Any
- Weight: 0.0044 ounce, 0.126 grams

Maximum Ratings @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

| Type number | Symbol | RMB2S | RMB4S | RMB6S | Units |
|---|-------------|-------|------------|-------|-------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} | 200 | 400 | 600 | V |
| RMS Reverse Voltage | V_{RMS} | 140 | 280 | 420 | V |
| Maximum average forward current 60Hz sine wave resistance load On glass-epoxy P.C.B. On aluminum substrate | $I_{F(AV)}$ | | 0.5 0.8 | | A |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | | 30 | | A |

Electrical Characteristics:

| Type number | Symbol | RMB2S | RMB4S | RMB6S | Units |
|---|----------|----------|-------|-------|---------|
| Maximum instantaneous forward voltage drop (Note 1)@ $I_F = 0.4A$ | V_F | 1.0 | | | V |
| Maximum DC reverse current $T_A = 25^\circ C$ at rated DC blocking voltage $T_A = 125^\circ C$ | I_R | 5 100 | | | μA |
| Maximum reverse recovery time(Note 2) | t_{rr} | 150 | | | nS |
| Typical junction capacitance (per leg) | C_j | 13 | | | pF |

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

| Type number | Symbol | RMB2S | RMB4S | RMB6S | Units |
|--|-----------------|-------------|-------|-------|--------------|
| Typical thermal resistance | $R_{\theta JA}$ | 85 | | | $^\circ C/W$ |
| Operating junction and storage temperature range | T_J, T_{STG} | -55 to +150 | | | $^\circ C$ |

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad..
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
 3. Thermal Resistance From Junction to Ambient

Ratings and Characteristics Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT FOR

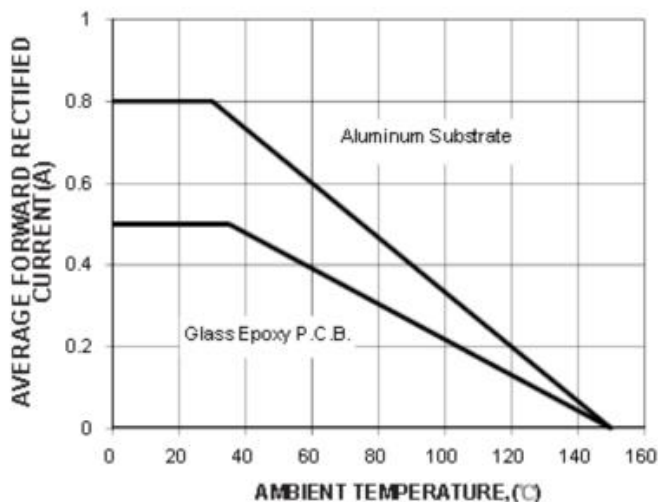
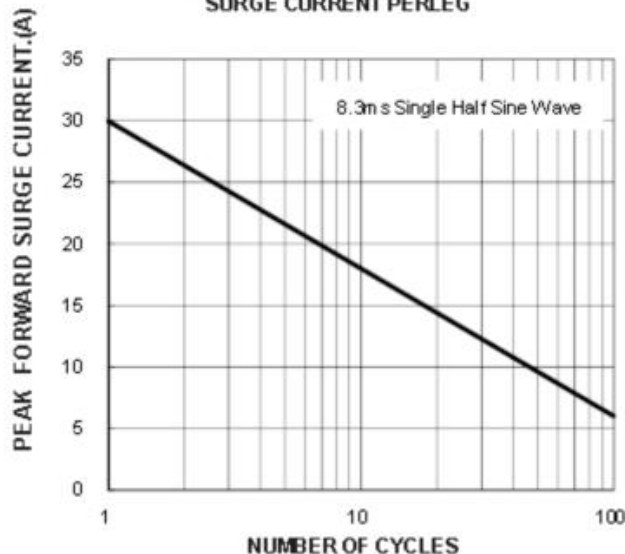
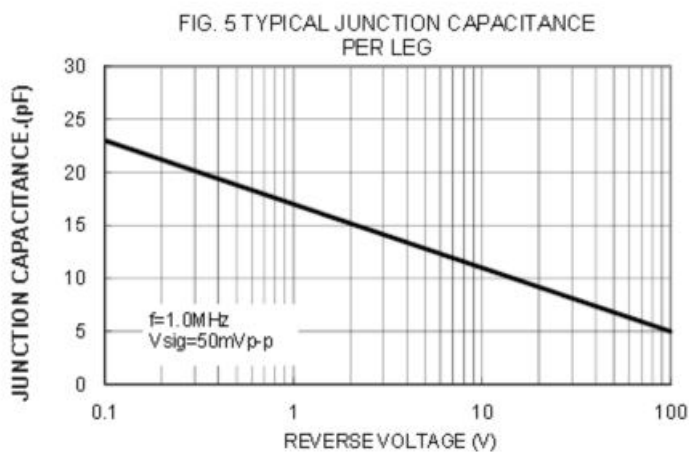
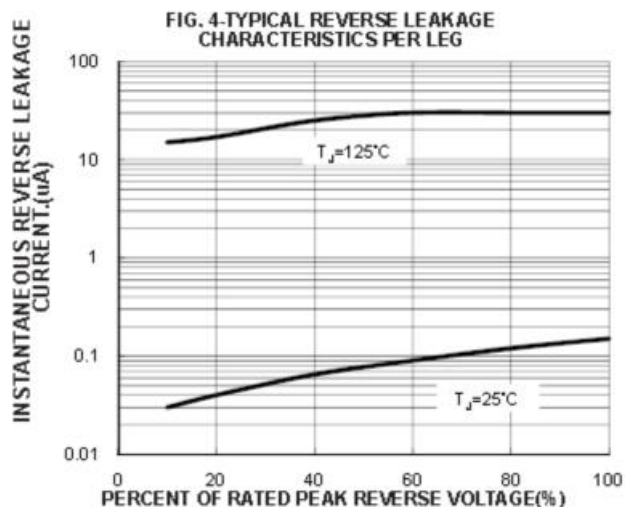
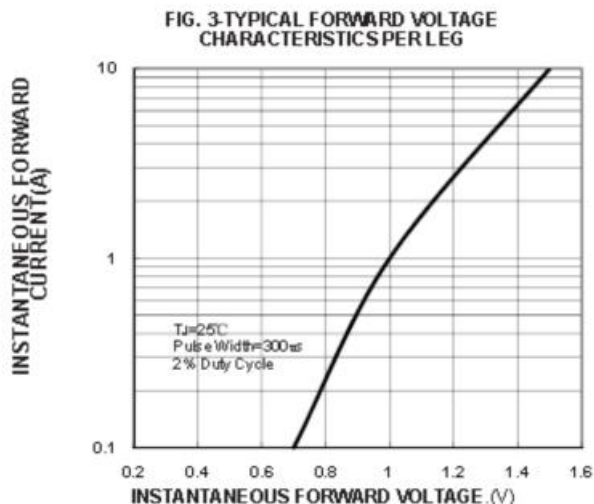


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG



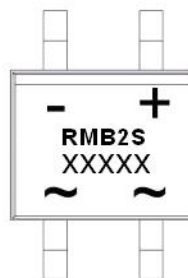


Ordering Information

| Device | Package | Plating | Shipping |
|------------------------|-------------------|---------|----------------|
| RMB2S THRU RMB6S | MB-S (Pb-Free) | Pure Sn | 3000pcs / reel |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

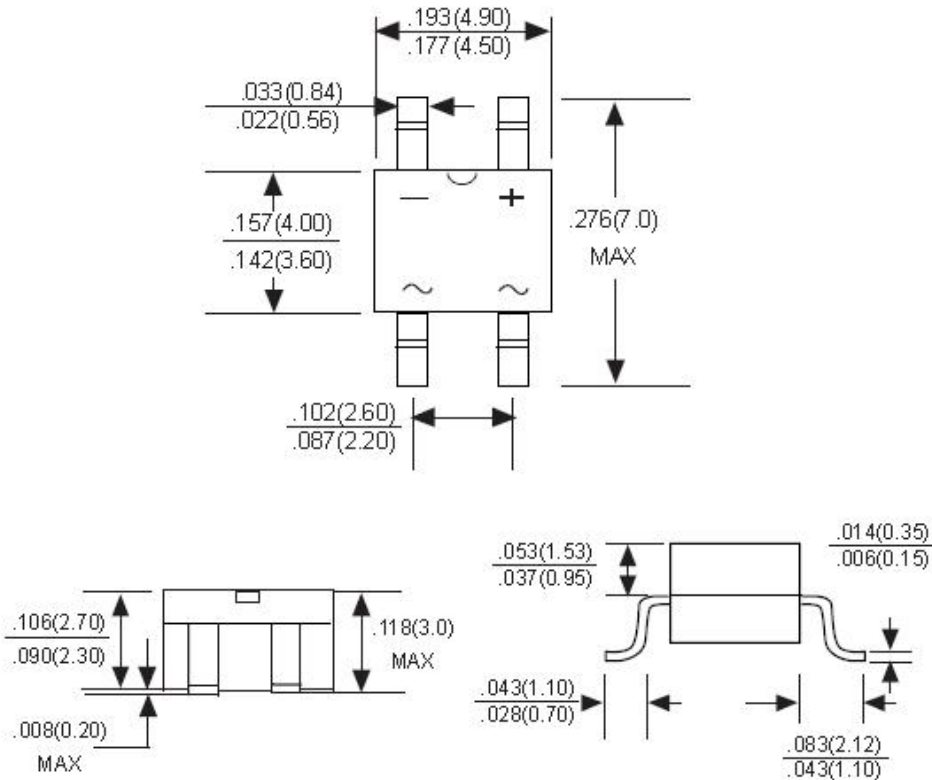


Where XXXXX is YYWWL

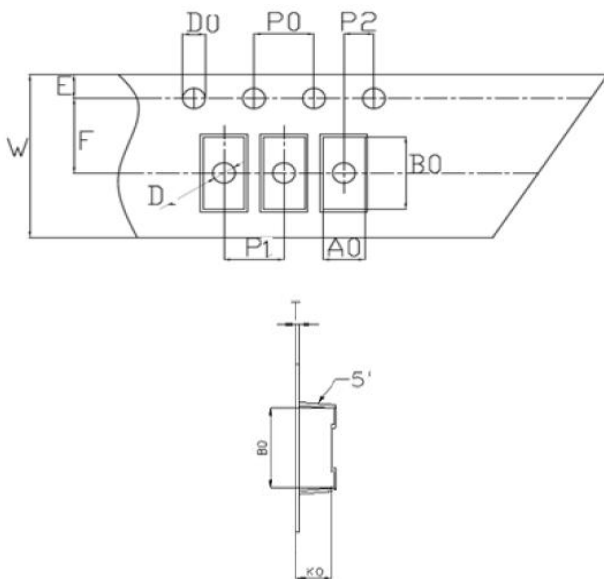
RMB2S = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Mechanical Dimensions MB-S(Inches/Millimeters)



Carrier Tape Specification MB-S



| SYMBOL | Millimeters | |
|--------|-------------|-------|
| | Min. | Max. |
| A0 | 4.92 | 5.12 |
| B0 | 7.12 | 7.32 |
| D0 | 1.50 | 1.60 |
| D1 | 1.40 | 1.60 |
| P0 | 3.90 | 4.10 |
| P1 | 7.90 | 8.10 |
| P2 | 1.95 | 2.05 |
| E | 1.65 | 1.85 |
| K0 | 2.78 | 2.98 |
| F | 5.45 | 5.55 |
| W | 11.90 | 12.10 |
| T | 0.24 | 0.30 |
| 10P0 | 39.80 | 40.20 |
| 抗拉拉力 | ≥3KG | |



RMB2S
THRU
RMB6S

Technical Data
Data Sheet N1961, Rev. A



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